

# DATA SHEET

**BT258S-800R**

Thyristors  
logic level

Product specification

October 2002



# Thyristors logic level

## BT258S-800R

### GENERAL DESCRIPTION

Passivated, sensitive gate thyristor in a plastic envelope, suitable for surface mounting, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

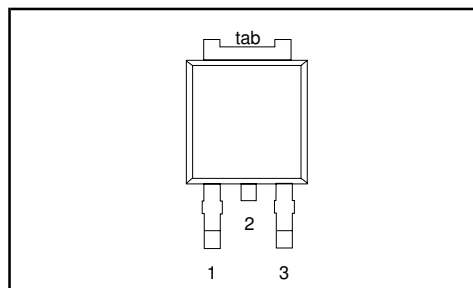
### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
$V_{DRM}, V_{RRM}$	Repetitive peak off-state voltages	800	V
$I_{T(AV)}$	Average on-state current	5	A
$I_{T(RMS)}$	RMS on-state current	8	A
$I_{TSM}$	Non-repetitive peak on-state current	75	A

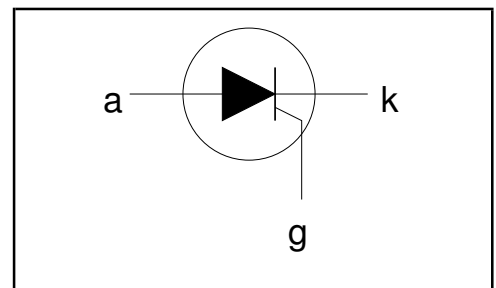
### PINNING - SOT428

PIN NUMBER	
1	cathode
2	anode
3	gate
tab	anode

### PIN CONFIGURATION



### SYMBOL



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DRM}, V_{RRM}$	Repetitive peak off-state voltages		-	800	V
$I_{T(AV)}$	Average on-state current	half sine wave; $T_{mb} \leq 111\text{ °C}$	-	5	A
$I_{T(RMS)}$	RMS on-state current	all conduction angles	-	8	A
$I_{TSM}$	Non-repetitive peak on-state current	half sine wave; $T_j = 25\text{ °C}$ prior to surge	-	75	A
		$t = 10\text{ ms}$	-	82	A
		$t = 8.3\text{ ms}$	-	28	A <sup>2</sup> s
		$t = 10\text{ ms}$	-	50	A/μs
$I^2t$	$I^2t$ for fusing	$I_{TM} = 10\text{ A}; I_G = 50\text{ mA};$ $dI_G/dt = 50\text{ mA}/\mu\text{s}$	-	-	-
$dI_T/dt$	Repetitive rate of rise of on-state current after triggering		-	50	A/μs
$I_{GM}$	Peak gate current		-	2	A
$V_{RGM}$	Peak reverse gate voltage		-	5	V
$P_{GM}$	Peak gate power		-	5	W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.5	W
$T_{stg}$	Storage temperature		-40	150	°C
$T_j$	Operating junction temperature		-	125 <sup>1</sup>	°C

<sup>1</sup> Note: Operation above 110 °C may require the use of a gate to cathode resistor of 1kΩ or less.

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**THERMAL RESISTANCES**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base		-	-	2.0	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	pcb (FR4) mounted; footprint as in Fig.14	-	75	-	K/W

**STATIC CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise stated

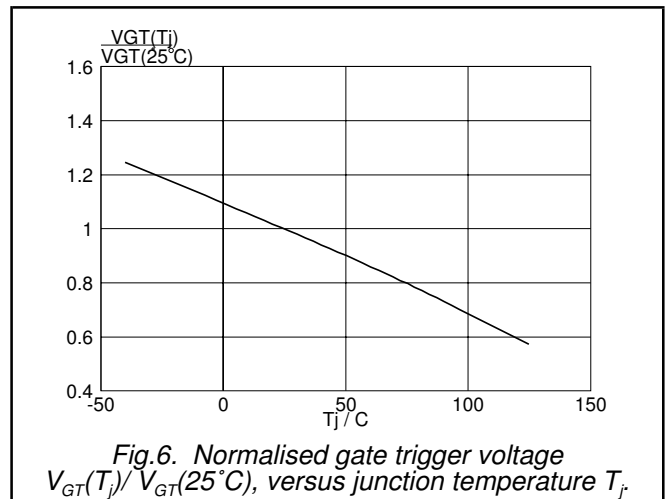
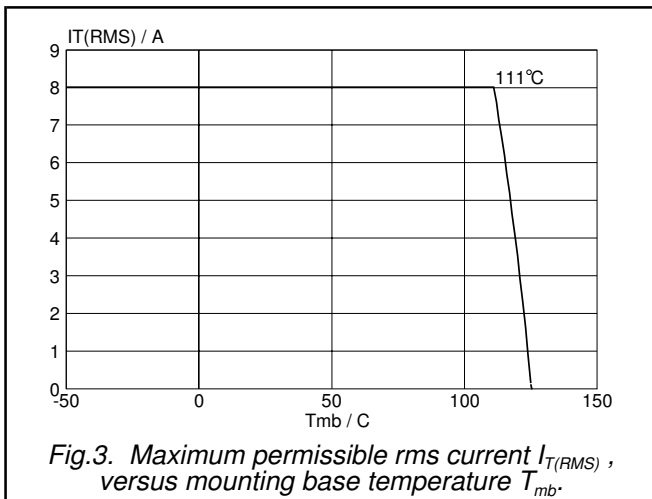
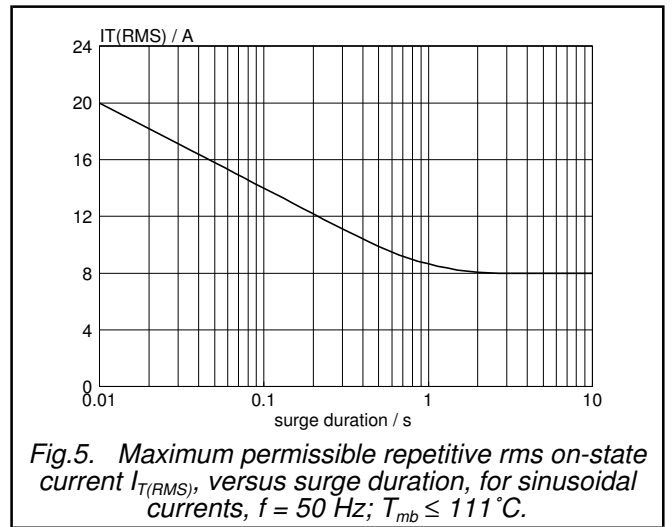
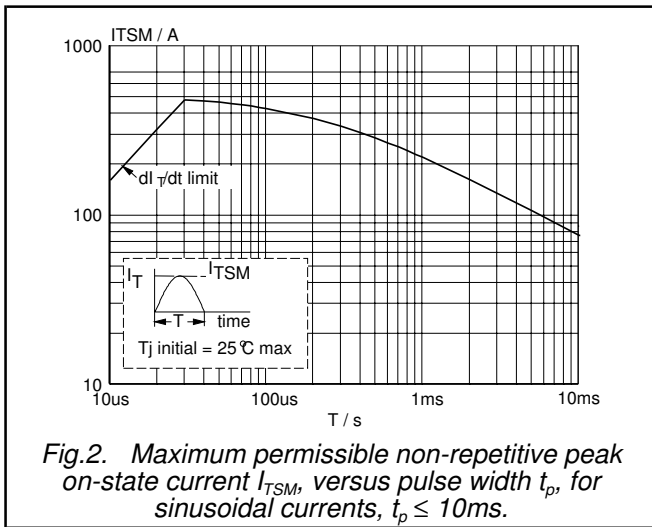
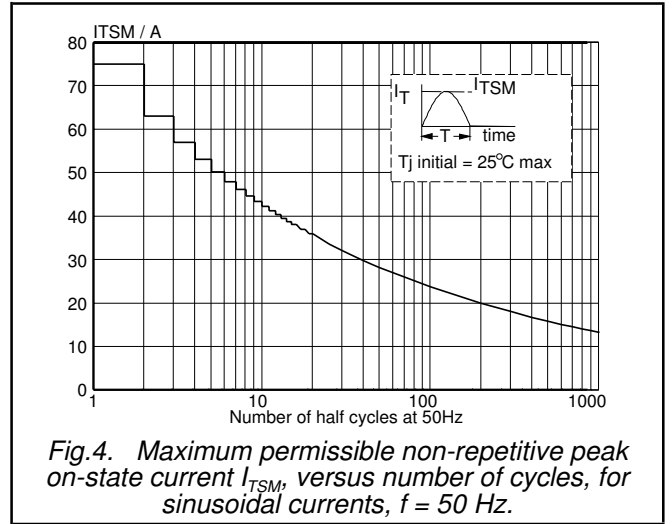
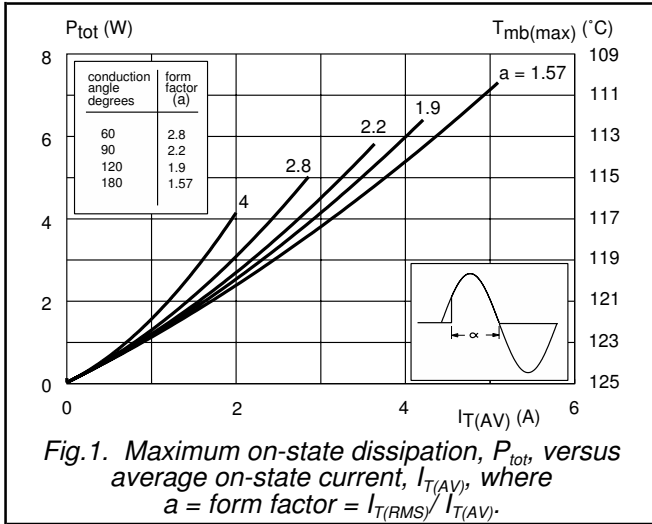
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{GT}$	Gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$	-	50	200	$\mu\text{A}$
$I_L$	Latching current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$	-	0.4	10	mA
$I_H$	Holding current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$	-	0.3	6	mA
$V_T$	On-state voltage	$I_T = 16\text{ A}$	-	1.3	1.6	V
$V_{GT}$	Gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$	-	0.4	1.5	V
$I_D, I_R$	Off-state leakage current	$V_D = V_{DRM(max)}; I_T = 0.1\text{ A}; T_j = 110\text{ °C}$ $V_D = V_{DRM(max)}; V_R = V_{RRM(max)}; T_j = 125\text{ °C}$	0.1	0.2	-	V
			-	0.1	0.5	mA

**DYNAMIC CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$dV_D/dt$	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125\text{ °C};$ exponential waveform; $R_{GK} = 100\ \Omega$	50	100	-	V/ $\mu\text{s}$
$t_{gt}$	Gate controlled turn-on time	$I_{TM} = 10\text{ A}; V_D = V_{DRM(max)}; I_G = 5\text{ mA};$ $dI_G/dt = 0.2\text{ A}/\mu\text{s}$	-	2	-	$\mu\text{s}$
$t_q$	Circuit commutated turn-off time	$V_D = 67\% V_{DRM(max)}; T_j = 125\text{ °C};$ $I_{TM} = 12\text{ A}; V_R = 24\text{ V}; dI_{TM}/dt = 10\text{ A}/\mu\text{s};$ $dV_D/dt = 2\text{ V}/\mu\text{s}; R_{GK} = 1\text{ k}\Omega$	-	100	-	$\mu\text{s}$

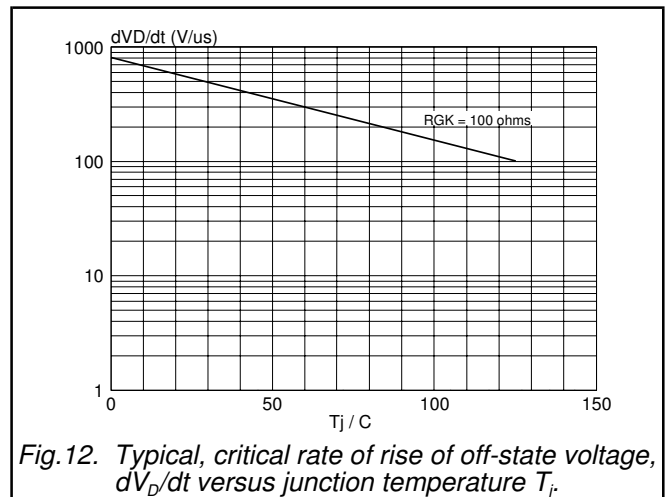
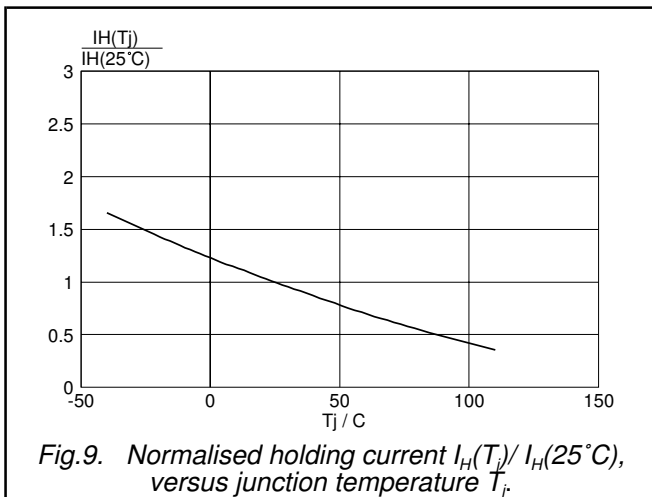
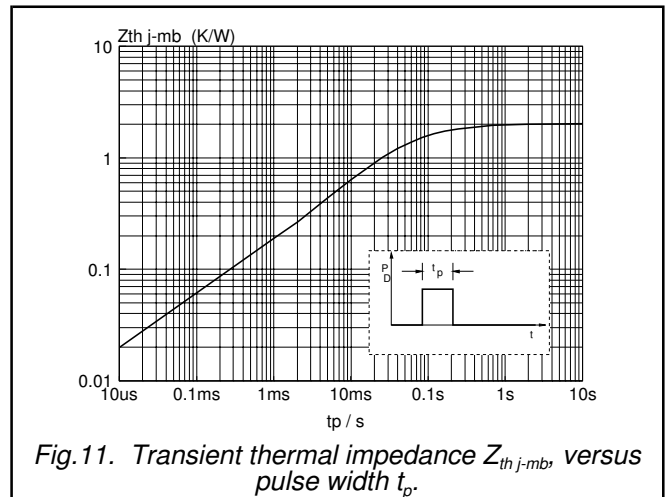
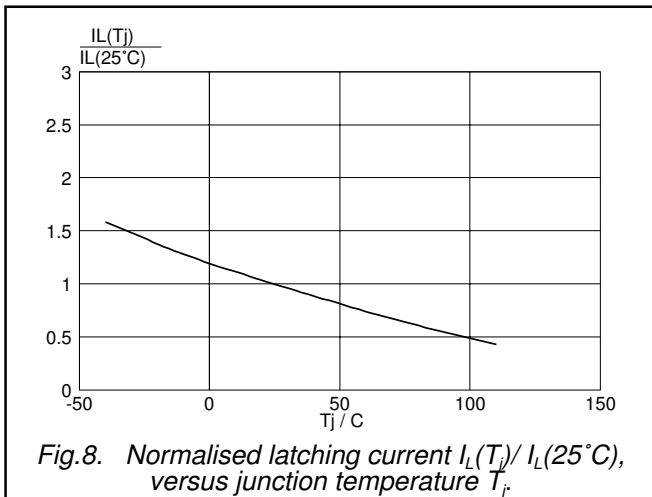
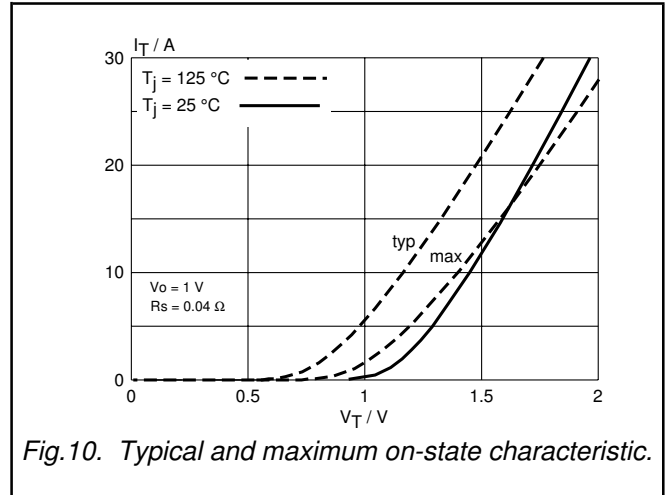
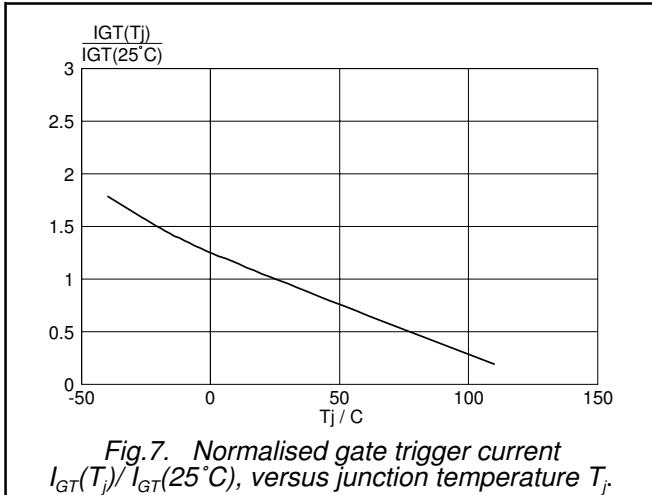
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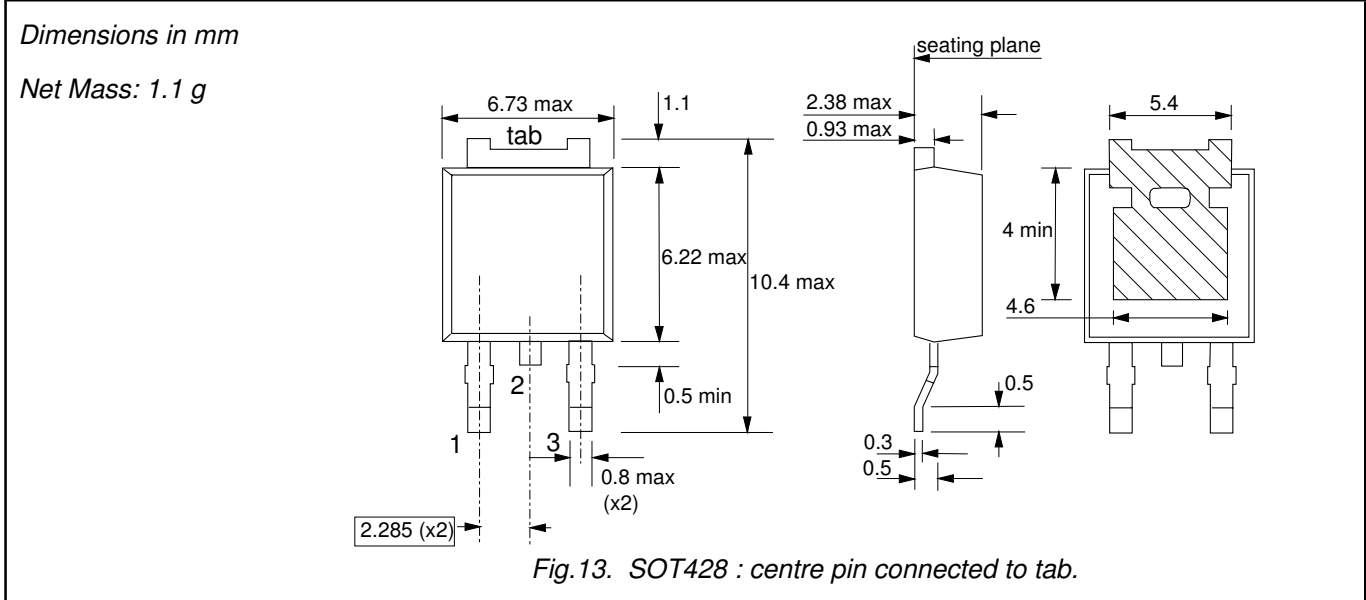


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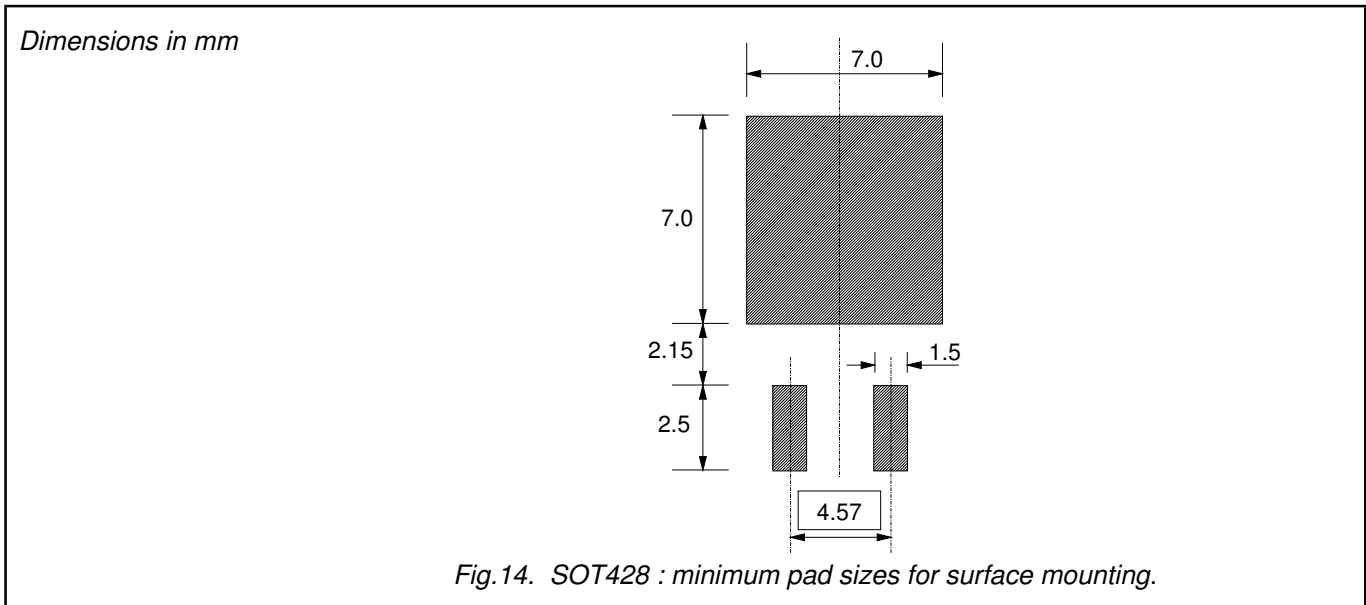
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**MECHANICAL DATA**



**MOUNTING INSTRUCTIONS**



**Notes**

- 1. Plastic meets UL94 V0 at 1/8".

## Legal information

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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